



Semiconductor Device Type: DPA 008 MSOP 3x3mm Matte Tin			Termination Base Alloy: Copper Alloy (Cu)			Package Homogeneous Materials: 8.1 Electronics (e.g. pc boards, displays)			J-STD-609A Product Marking and/or Pkg. Labeling e3	
Basic Substance	CAS Number	Contained in Sub-Component	% Total Weight	mg/part	ppm	13.30 (mg) Total	Mold Compound	% of Total Weight	53.00	
Silica, vitreous	60676-86-0	Mold Compound	45.050	11.308	450,500		Silica, vitreous 60676-86-0	85.00		
Epoxy Resin	Trade Secret	Mold Compound	3.246	0.815	32,463		Epoxy Resin Trade Secret	6.13		
Phenolic Resin	Trade Secret	Mold Compound	3.246	0.815	32,463		Phenolic Resin Trade Secret	6.13		
Epoxy, Cresol Novolac	29690-82-2	Mold Compound	1.299	0.326	12,985		Epoxy, Cresol Novolac 29690-82-2	2.45		
Carbon Black	1333-86-4	Mold Compound	0.159	0.040	1,590		Carbon Black 1333-86-4	0.30		
Copper	7440-50-8	Lead Frame	39.096	9.813	390,964					
Nickel	7440-02-0	Lead Frame	1.043	0.262	10,427	10.30 (mg) Total	Lead Frame	% of Total Weight	41.05	
Silicon	7440-21-3	Lead Frame	0.185	0.046	1,847		Copper 7440-50-8	95.24		
Magnesium	7439-95-4	Lead Frame	0.041	0.010	411		Nickel 7440-02-0	2.54		
Silver	7440-22-4	Lead Frame	0.685	0.172	6,851		Silicon 7440-21-3	0.45		
Silver (Ag)	7440-22-4	Die Attach	0.912	0.229	9,120		Magnesium 7439-95-4	0.10		
Epoxy Resin	Trade Secret	Die Attach	0.228	0.057	2,280		Silver 7440-22-4	1.67		
Silicon	7440-21-3	Chip (Die)	2.550	0.640	25,500					
Gold	7440-57-5	Wire Bond	0.420	0.105	4,200	0.29 (mg) Total	Die Attach	% of Total Weight	1.14	
Tin	7440-31-5	Plating on external leads (pins) - Matte Tin / annealed at 150°C for 1 hour	1.840	0.462	18,400		Silver (Ag) 7440-22-4	80.00		
<b>TOTALS:</b>			<b>100.000</b>	<b>25.100</b>	<b>1,000,000</b>		Epoxy Resin Trade Secret	20.00		
<b>0.0251g Total Mass</b>										
<p>This semiconductor device and its homogenous materials comply with EU Directives: 2002/95/EC (27 January 2003) &amp; Directive 2011/65/EU (08 June 2011) and 2015/863/EU (31 March 2015) and 2000/53/EC and 2016/774/EU (End-of-Life Vehicles (ELV) without exemption (zero))</p> <p>Compliance with the above EU Directives has been verified via internal design controls, supplier declarations, and /or analytical test data.</p> <p>If a chemical substance is absent from the list above, the chemical substance is NOT an intentional ingredient in the semiconductor device and, to the best of Microchip Technology Incorporated's knowledge and belief as of the date of this document, there is no credible reason to believe that the unavoidable impurity concentration of the chemical substance, if any, is not below the threshold of regulatory concern for any regulatory scheme world-wide.</p> <p>Molding compounds used by Microchip meet the UL94 V0 flammability standard for plastics. You can access the UL IQTM family of databases to obtain a test report at <a href="http://ul.com/global/eng/pages/offerings/industries/chemicals/plastics/">http://ul.com/global/eng/pages/offerings/industries/chemicals/plastics/</a></p> <p>The protective "tubes" in which the specific product is shipped are made from polyvinyl chloride (PVC) plastic. "Window envelopes" used to hold the packing slip on the outer box and certain "reels" may be made from PVC plastic.</p> <p>Microchip Technology Incorporated believes the information in this form concerning substances restricted by RoHS in Microchip Technology Incorporated's semiconductor devices in their original packing materials is true and correct to the best of its knowledge and belief, as of the date listed in this form. Microchip Technology Incorporated cannot guarantee the completeness and accuracy of data in this form because it has been compiled based on the ranges provided in Material Safety Data Sheets provided by raw material suppliers. Supplier information is often protected from disclosure as trade secrets and some information may not have been provided by subcontract assemblers and raw material suppliers. Information is provided only as estimates of the average weight of these parts and the average weight of anticipated significant toxic metals components. These estimates do not include trace levels of dopants, metals, and non-metal materials contained within silicon devices (silicon IC) in the finished parts.</p> <p>Microchip Technology Incorporated does not provide any warranty, express or implied, with respect to the information provided in this declaration. The exclusive, limited product warranties provided by Microchip Technology Incorporated and its subsidiaries are contained in Microchip's standard terms and conditions of sale. These are provided in Microchip's quotations, sales order acknowledgement, and invoices.</p> <p>Microchip disclaims any duty to notify users of updates or changes to Material Content Declarations and shall not be liable for any damages, direct or indirect, consequential or otherwise, suffered by users or third parties as a result of the users' reliance on the information in Material Content Declarations (MCD) or independent third party test reports (SGS) or of this Certificate of Compliance for semiconductor products.</p> <p>Assembled package referenced above is EU REACH compliant based on the latest SVHC candidate list of ECHA which can be found at <a href="http://echa.europa.eu/web/guest/candidate-list-table">http://echa.europa.eu/web/guest/candidate-list-table</a></p>						0.64	Total (mg)	Chip (Die)	% of Total Weight	2.55
		Doped Silicon	7440-21-3	100.00						
		Total			100.00					
0.11	(mg) Total	Wire Bond	% of Total Weight	0.42						
		Gold	7440-57-5	100.00						
		Total			100.00					
0.46	(mg) Total	Plating on external leads (pins) - Matte Tin / annealed at 150°C for 1 hour	% of Total Weight	1.84						
		Tin	7440-31-5	100.00						
		Total			100.00					